

SOT906-1

plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN88
Package type industry code	HVQFN88
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-8-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	88	-	

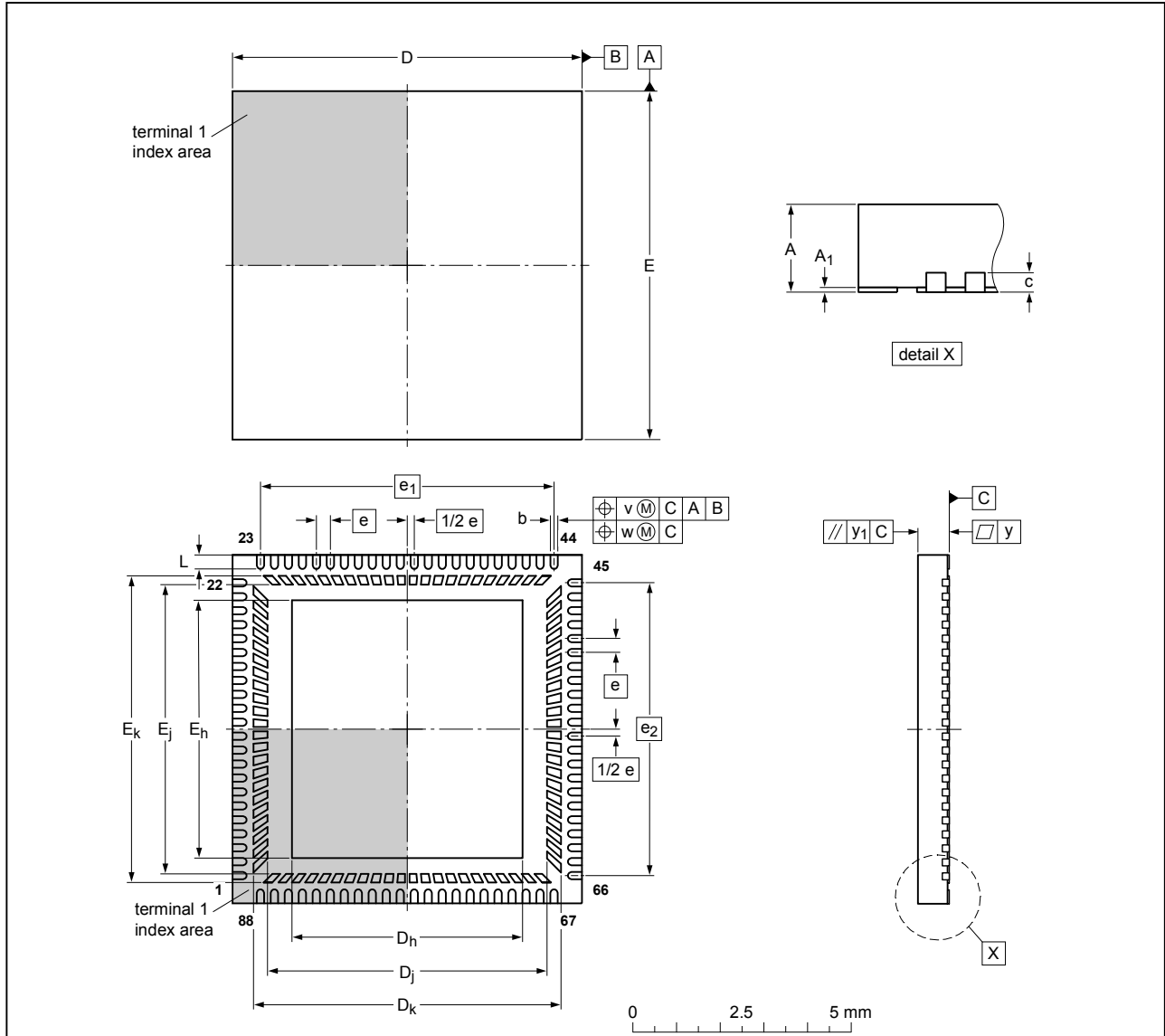


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2. Package outline

HVQFN88: plastic thermal enhanced very thin quad flat package; no leads; 88 terminals; body 10 x 10 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	b	c	D ⁽¹⁾	D _h	D _j	D _k	E ⁽¹⁾	E _h	E _j	E _k	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.25 0.15	0.2	10.1 9.9	6.75 6.45	8.1 7.9	8.9 8.7	10.1 9.9	7.55 7.25	8.4 8.2	8.9 8.7	0.4	8.4	8.4	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT906-1	---	---	---		05-07-29 05-08-09

Fig. 1. Package outline HVQFN88 (SOT906-1)

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3. Legal information

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